

**AMENDMENTS****IN THE SPECIFICATION:**

Amend the paragraph beginning at page 38, line 23, as follows.

In pressure-sensing portion 30 of the pulse wave measuring apparatus in the present embodiment, base portion ~~[[42]]~~ 44 serving as the inner frame body and cap portion ~~[[44]]~~ 46 serving as the outer frame body are formed with a ceramic material. If base portion ~~[[42]]~~ 44 and cap portion ~~[[44]]~~ 46 are formed with the ceramic material which is a material attaining high thermal conductivity, heat produced by current flow in the pressure-sensing device provided in semiconductor substrate 1 is effectively dissipated by base portion ~~[[42]]~~ 44 and cap portion ~~[[44]]~~ 46 through support member 9, which leads to suppression of temperature increase on the surface of pressure-sensing portion 30. Therefore, a pulse wave measuring apparatus less likely to cause cold burn and excellent in safety can be provided.